

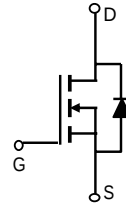
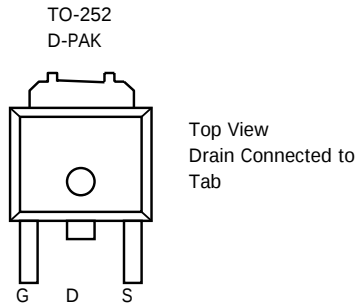
AOD400
N-Channel Enhancement Mode Field Effect Transistor

General Description

The AOD400 uses advanced trench technology and design to provide excellent $R_{DS(ON)}$ with low gate charge. This device is suitable for use in PWM, load switching and general purpose applications. *Standard Product AOD400 is Pb-free (meets ROHS & Sony 259 specifications). AOD400L is a Green Product ordering option. AOD400 and AOD400L are electrically identical.*

Features

$V_{DS} (V) = 30V$
 $I_D = 10 A (V_{GS} = 10V)$
 $R_{DS(ON)} < 30 m\Omega (V_{GS} = 10V)$
 $R_{DS(ON)} < 36 m\Omega (V_{GS} = 4.5V)$
 $R_{DS(ON)} < 52 m\Omega (V_{GS} = 2.5V)$


Absolute Maximum Ratings $T_A=25^\circ C$ unless otherwise noted

Parameter	Symbol	Maximum	Units
Drain-Source Voltage	V_{DS}	30	V
Gate-Source Voltage	V_{GS}	± 12	V
Continuous Drain Current ^G	I_D	10	A
$T_C=25^\circ C$			
$T_C=100^\circ C$	I_D	10	A
Pulsed Drain Current ^C	I_{DM}	40	
Avalanche Current ^C	I_{AR}	15	A
Repetitive avalanche energy $L=0.1mH$ ^C	E_{AR}	30	mJ
Power Dissipation ^B	$T_C=25^\circ C$	P_D	20
	$T_C=100^\circ C$		10
Power Dissipation ^A	$T_A=25^\circ C$	P_{DSM}	2.1
	$T_A=70^\circ C$		1.3
Junction and Storage Temperature Range	T_J, T_{STG}	-55 to 175	$^\circ C$

Thermal Characteristics

Parameter	Symbol	Typ	Max	Units
Maximum Junction-to-Ambient ^A	$R_{\theta JA}$	17.4	30	$^\circ C/W$
$t \leq 10s$				
Maximum Junction-to-Ambient ^A		50	60	$^\circ C/W$
Steady-State				
Maximum Junction-to-Case ^B	$R_{\theta JC}$	4	7.5	$^\circ C/W$
Steady-State				

Electrical Characteristics (T_j=25°C unless otherwise noted)

Symbol	Parameter	Conditions	Min	Typ	Max	Units
STATIC PARAMETERS						
BV _{DSS}	Drain-Source Breakdown Voltage	I _D =250μA, V _{GS} =0V	30			V
I _{DSS}	Zero Gate Voltage Drain Current	V _{DS} =24V, V _{GS} =0V T _J =55°C		0.002	1 5	μA
I _{GSS}	Gate-Body leakage current	V _{DS} =0V, V _{GS} = ±12V			100	nA
V _{GS(th)}	Gate Threshold Voltage	V _{DS} =V _{GS} I _D =250μA	0.7	1.1	1.4	V
I _{D(ON)}	On state drain current	V _{GS} =4.5V, V _{DS} =5V	40			A
R _{DS(ON)}	Static Drain-Source On-Resistance	V _{GS} =10V, I _D =10A T _J =125°C		25 35	30 42	mΩ
		V _{GS} =4.5V, I _D =10A		28.5	36	mΩ
		V _{GS} =2.5V, I _D =5A		40.5	52	mΩ
g _{FS}	Forward Transconductance	V _{DS} =5V, I _D =10A		21		S
V _{SD}	Diode Forward Voltage	I _S =1A, V _{GS} =0V		0.77	1	V
I _S	Maximum Body-Diode Continuous Current				3	A
DYNAMIC PARAMETERS						
C _{iss}	Input Capacitance	V _{GS} =0V, V _{DS} =15V, f=1MHz		857	1030	pF
C _{oss}	Output Capacitance			97		pF
C _{rss}	Reverse Transfer Capacitance			71		pF
R _g	Gate resistance	V _{GS} =0V, V _{DS} =0V, f=1MHz		1.4	3.6	Ω
SWITCHING PARAMETERS						
Q _g	Total Gate Charge	V _{GS} =10V, V _{DS} =15V, I _D =10A		9.7	12	nC
Q _{gs}	Gate Source Charge			1.63		nC
Q _{gd}	Gate Drain Charge			3.1		nC
t _{D(on)}	Turn-On DelayTime	V _{GS} =10V, V _{DS} =15V, R _L =1.5Ω, R _{GEN} =6Ω		3.5		ns
t _r	Turn-On Rise Time			3.7		ns
t _{D(off)}	Turn-Off DelayTime			25		ns
t _f	Turn-Off Fall Time			4		ns
t _{rr}	Body Diode Reverse Recovery Time	I _F =10A, dI/dt=100A/μs		20	24	ns
Q _{rr}	Body Diode Reverse Recovery Charge	I _F =10A, dI/dt=100A/μs		13		nC

A: The value of R_{θJA} is measured with the device mounted on 1in² FR-4 board with 2oz. Copper, in a still air environment with T_A=25°C. The Power dissipation P_{DSM} is based on R_{θJA} and the maximum allowed junction temperature of 150°C. The value in any given application depends on the user's specific board design, and the maximum temperature of 175°C may be used if the PCB allows it.

B: The power dissipation P_D is based on T_{J(MAX)}=175°C, using junction-to-case thermal resistance, and is more useful in setting the upper dissipation limit for cases where additional heatsinking is used.

C: Repetitive rating, pulse width limited by junction temperature T_{J(MAX)}=175°C.

D: The R_{θJA} is the sum of the thermal impedance from junction to case R_{θJC} and case to ambient.

E: The static characteristics in Figures 1 to 6 are obtained using <300 μs pulses, duty cycle 0.5% max.

F: These curves are based on the junction-to-case thermal impedance which is measured with the device mounted to a large heatsink, assuming a maximum junction temperature of T_{J(MAX)}=175°C.

G: The maximum current rating is limited by bond-wires.

H: These tests are performed with the device mounted on 1 in² FR-4 board with 2oz. Copper, in a still air environment with T_A=25°C. The SOA curve provides a single pulse rating.

Rev 0 : Aug 2005

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TYPICAL ELECTRICAL AND THERMAL CHARACTERISTICS

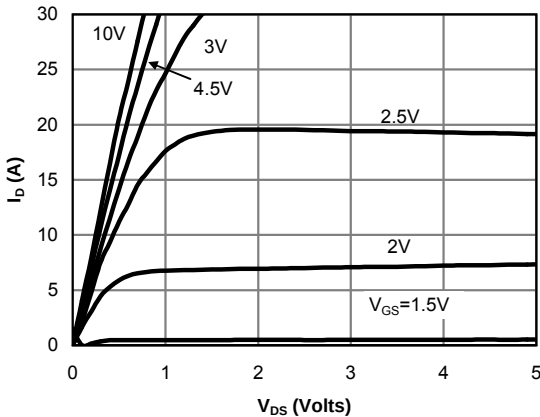


Fig 1: On-Region Characteristics

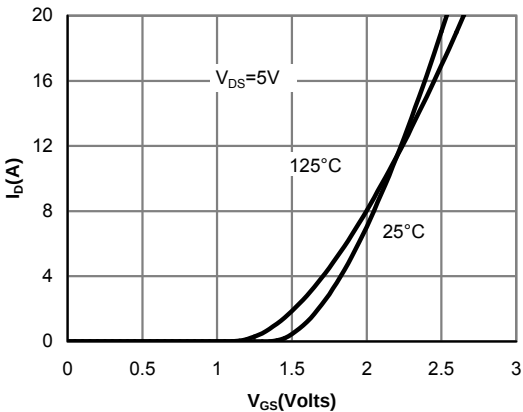


Figure 2: Transfer Characteristics

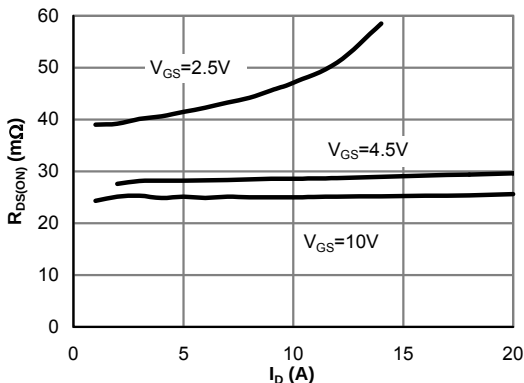


Figure 3: On-Resistance vs. Drain Current and Gate Voltage

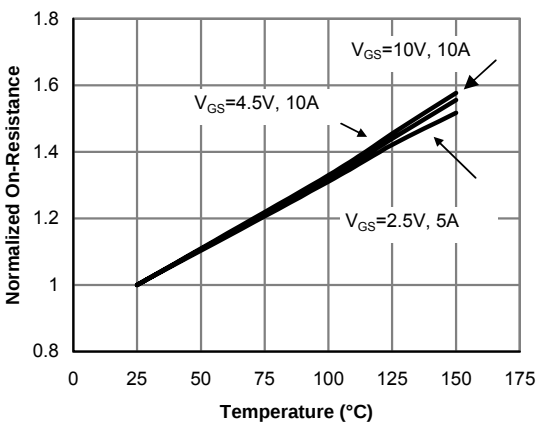


Figure 4: On-Resistance vs. Junction Temperature

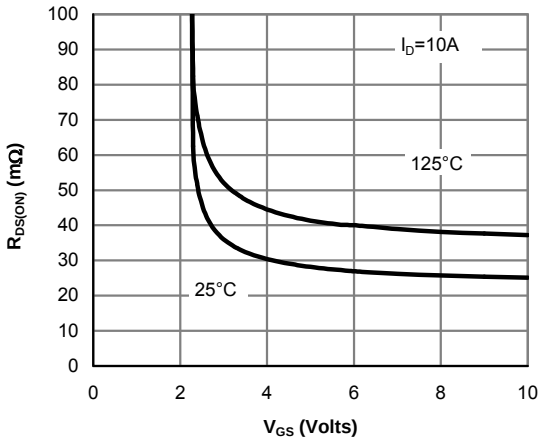


Figure 5: On-Resistance vs. Gate-Source Voltage

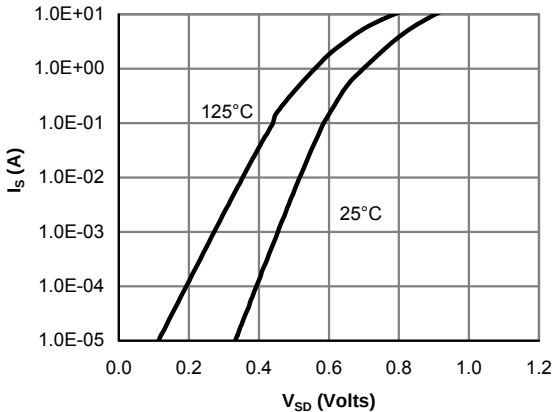


Figure 6: Body-Diode Characteristics

TYPICAL ELECTRICAL AND THERMAL CHARACTERISTICS

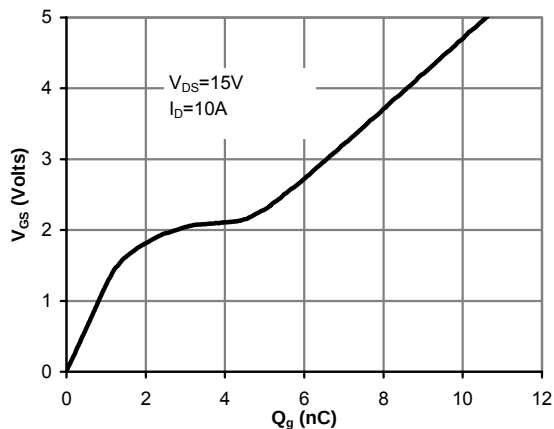


Figure 7: Gate-Charge Characteristics

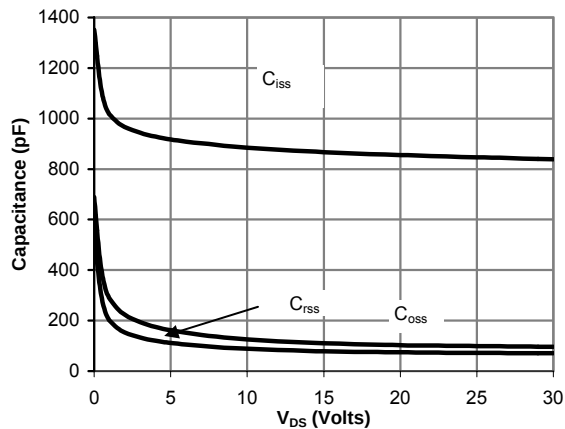


Figure 8: Capacitance Characteristics

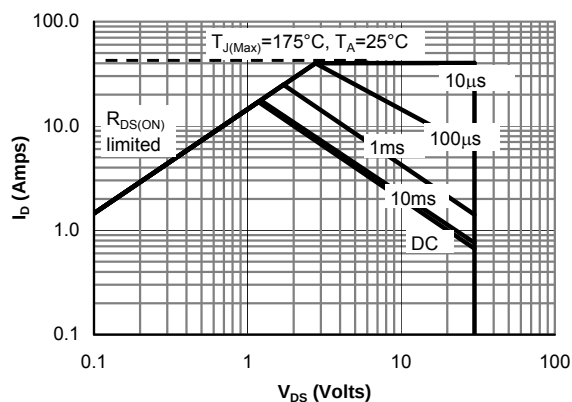


Figure 9: Maximum Forward Biased Safe Operating Area (Note F)

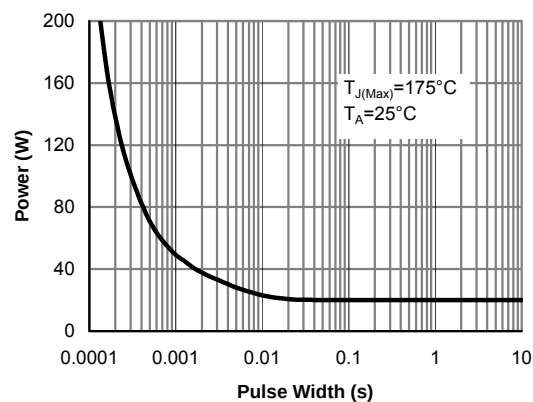


Figure 10: Single Pulse Power Rating Junction-to-Case (Note F)

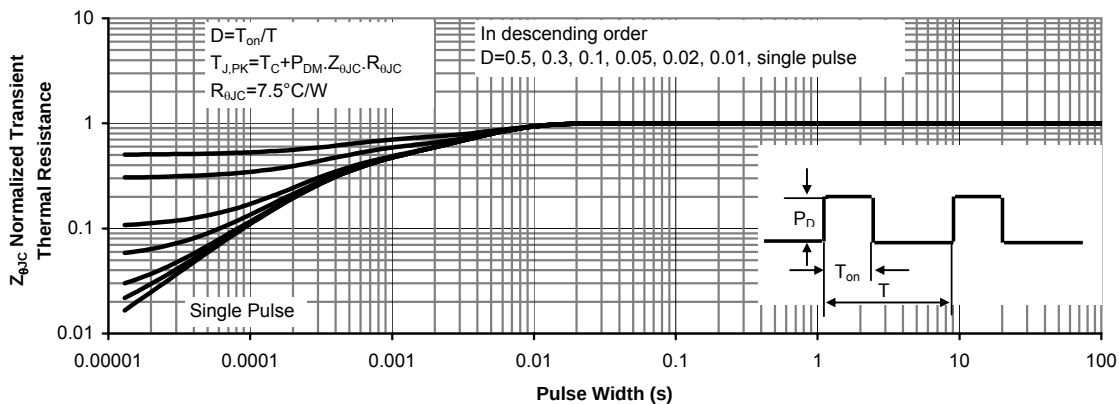


Figure 11: Normalized Maximum Transient Thermal Impedance (Note F)

TYPICAL ELECTRICAL AND THERMAL CHARACTERISTICS

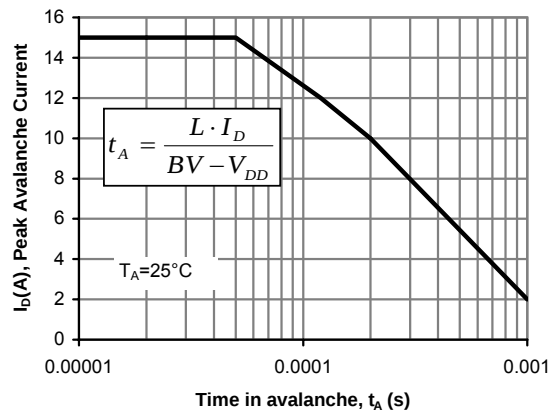


Figure 12: Single Pulse Avalanche capability

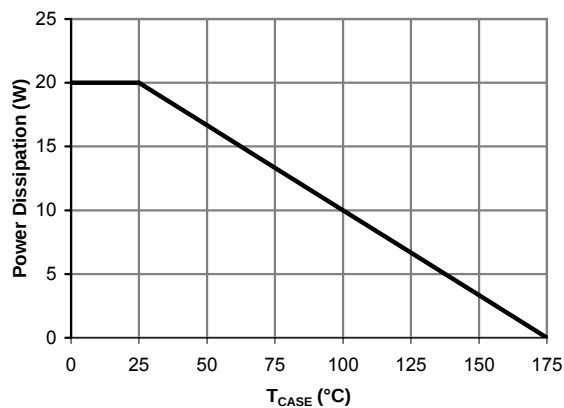


Figure 13: Power De-rating (Note B)

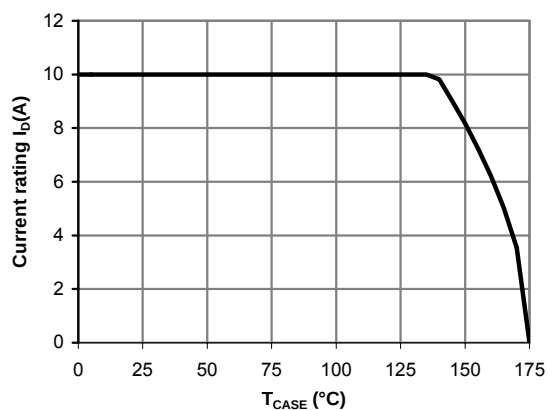


Figure 14: Current De-rating (Note B)

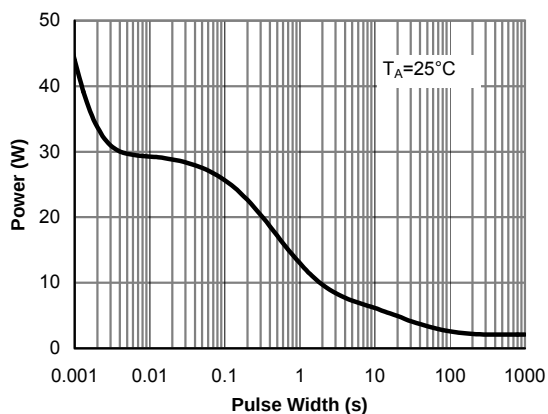


Figure 15: Single Pulse Power Rating Junction-to-Ambient (Note H)

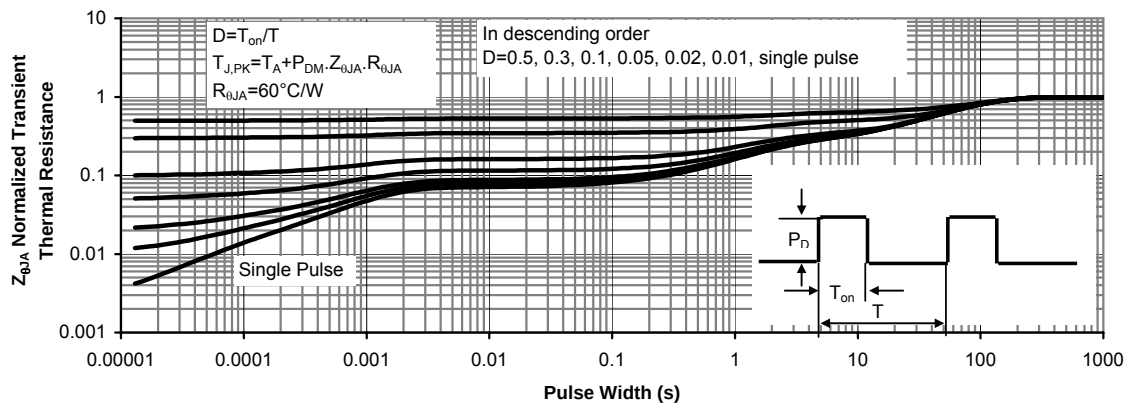


Figure 16: Normalized Maximum Transient Thermal Impedance (Note H)